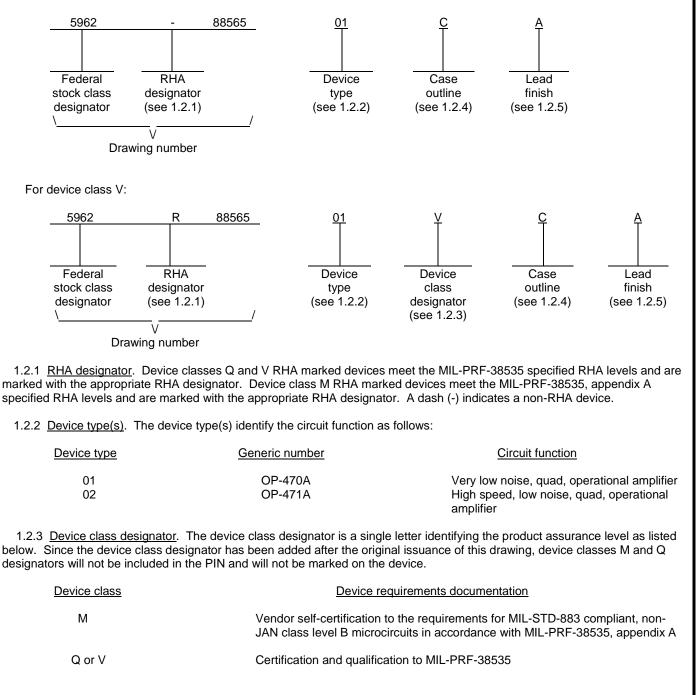
| | | | | | | | F | REVISI | UNS | | | | | | | | | | |
|---|--|-------------------------|---|---|--|--------------------------|-----------|----------|----------------------------|---------------------|---------------------------------------|--------------------------------------|---|------------------------------------|--|------------------------|-----------------|--------|----|
| LTR | DESCRIPTION | | | | | DA | TE (YI | R-MO-E | DA) | | APPF | ROVED |) | | | | | | |
| А | Add case of changes the | | | ice typ | es 01 a | and 02. | Upda | te form | at. Edi | torial | | | 89-11 | -07 | | | M. A | . Frye | |
| В | Changes to Changes L | | | | | st and t | to the c | output v | voltage | swing t | est. | | 93-08 | 8-26 | | | M. A | . Frye | |
| С | Add case o delta test li | | | | lerplate | e to add | l one-p | art part | numbe | ers. Ad | d | | 96-11 | -25 | | | R. M | 1onnin | |
| D | Add radiat | on hardr | ness rea | quirem | nents. I | Update | boilerp | olate | rrp | | | | 98-06 | 6-19 | | | R. N | Ionnin | |
| Е | Change to | the slew | / rate te | est con | dition A | A _{VCL} in t | able I. | -rrp | | | | | 00-10 |)-04 | | | R. N | Ionnin | |
| F | Add case of 1.2.4, 1.3, requirement | outline D 3.2.3, fig | . Remo jure 1, a | ove rad | diation | exposu | ire circi | uit. Cha | anges i o reflec | made to t currer | o nt | | 03-03 | 3-19 | | | R. M | Ionnin | |
| G | Update dra | wing to | | requir | ements | s. Dele | ted uni | used gr | oup E | boilerpl | ate | | 11-0 | 4-06 | | | C. \$ | Saffle | |
| | | | | | | | | | | | | | | | | | | | |
| THE ORIGINAI REV SHEET REV SHEET | | ET OF T | | | IG HAS | | | | | | | | | | | | | | |
| REV SHEET REV SHEET REV STATUS | | ET OF T | REV | | IG HAS | G | G | G | G | G | G | G | G | G | G | G | | | |
| REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A | 3 | ET OF T | REV | | DBY | | | | | G 5 | 6 | 7 DLA I | 8 _AND | 9 AND | 10 MAR | 11 11 | _ | | |
| REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A | | | REV SHEI PREF Ga CHEC | ET | D BY BY | G | G | G | G | - | 6 | 7 DLA I DLUM | 8 _AND BUS, | 9 AND OHIC | 10 | 11 (ITIMI 218-39 | _ | | |
| REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DR/ THIS DRAWII FOR U DEPA AND AGET | | NBLE | REV SHEI PREF Ga CHEC Ra APPR Mi | ET PAREI ary Zal CKED ay Mor ROVEI ichael | D BY hn BY D BY A. Frye | G 1 | G 2 | G | G 4 MIC HAI | 5 ROC RDEN | | 7 DLA I DLUM http JIT, L | AND BUS, ://ww | 9 9 0 AND 0 OHIC 7w.ds | 10 MAR D 432 | 11 218-39 a.mil | 990 9 | | AL |
| REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DR/ THIS DRAWIN FOR U DEPA AND AGEN DEPARTMEN | NDARD OCIRCUIT AWING JSE BY ALL ARTMENTS INCIES OF TH | NBLE | REV SHEI PREF Ga CHEC Ra APPR Mi DRAV | ET PAREI ary Zal CKED ay Mor ROVEI ichael WING | D BY hn D BY A. Frye APPRC 88-0 | G 1 DVAL D 8-18 | G 2 | G | G 4 MIC HAI AM | 5 ROC RDEN | 6 I CC IRCU IED, ER, I | 7 DLA I DLUM http JIT, L | -AND BUS, ://ww -INE/ / NOI OLIT | 9 9 0 AND 0 OHIC 7w.ds | 10 MAR D 432 cc.dla CC.dla RADIA QUAE SILIC | 11 218-39 a.mil | 990 N ERA | | AL |

1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:



| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|--|-----------|---------------------|------------|
| DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 | | REVISION LEVEL G | SHEET 2 |

1.2.4 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

| Outline letter | Descriptive designator | Terminals | Package style |
|----------------|------------------------|-----------|------------------------------|
| С | GDIP1-T14 or CDIP2-T14 | 14 | Dual-in-line |
| D | GDFP1-F14 or CDFP2-F14 | 14 | Flat pack |
| 2 | CQCC1-N20 | 20 | Square leadless chip carrier |
| 3 | CQCC1-N28 | 28 | Square leadless chip carrier |
| К | GDFP2-F24 or CDFP3-F24 | 24 | Flat pack |

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

| Supply voltage (V _{CC}) Differential input voltage Differential input current Input voltage Output short circuit duration | ±1 V dc <u>2</u> / ±25 mA <u>2</u> / Supply voltage Continuous |
|---|---|
| Storage temperature range | |
| Lead temperature (soldering, 60 seconds) Power dissipation (P _D): | +300 C |
| Cases C and 2 Case D Case D Case 3 Case K Maximum junction temperature (T _J) Thermal resistance, junction-to-case (θ _{JC}) Thermal resistance, junction-to-ambient (θ _{JA}): | 500 mW 440 mW +150°C |
| Cases C and 2 | |
| Case D | |
| Case 3 | 110°C/W |
| Case K | 69°C/W |

1.4 Recommended operating conditions.

| Ambient operating temperature range (T _A) | -55°C to +125°C |
|---|-----------------|
| Supply voltage (V _{CC}) | ±15 V |

1.5 Radiation features.

Maximum total dose available (dose rate = 50 - 300 rads(Si)/s)..... 100 Krads(Si) 3/

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ The inputs are protected by back-to-back diodes. Current limiting resistors are not used in order to achieve low noise performance. If the differential input voltage exceeds ±1 V, the input current should be limited to ±25 mA.

3/ These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, Method 1019, condition A.

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|--|-----------|---------------------|------------|
| DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 | | REVISION LEVEL G | SHEET 3 |

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits. MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <u>https://assist.daps.dla.mil/quicksearch/</u> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein .

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 <u>Radiation exposure circuit</u>. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|--|-----------|---------------------|----------------|
| DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 | | REVISION LEVEL G | SHEET 4 |

| | T. | ABLE I. <u>Electric</u> | cal perfo | ormance | e characte | eristics | <u>.</u> | | | |
|-------------------------------|-------------------|---|---------------------|------------------|----------------|----------------|----------------|------|-------|-----------|
| Test | Symbol | $\begin{array}{c} Conditio\\ -55^{\circ}C \leq T_{\mu}\\ unless \ otherw \end{array}$ | °C | Group subgrou | | Device type | Li | mits | Unit | |
| | | | | | | | | Min | Max | |
| Input offset voltage | VIO | | | | 1 | | 01 | | ±0.4 | mV |
| | | | _ | | 2, 3 | | | | ±0.6 | |
| | | | M,D,P | ,L,R | 1 | | | | ±0.6 | |
| | | | | | 1 | | 02 | | ±0.8 | |
| | | | | | 2, 3 | | | | ±1.2 | - |
| | | | M,D,P | ,L,R | 1 | | | | ±1.0 | - |
| Input offset current | I _{IO} | V _{CM} = 0 V | 1 | | 1 | | All | | ±10 | nA |
| | | | | | 2, 3 | | | | ±20 | |
| | | | M,D,P | ,L,R | 1 | | | - | 50 | |
| Input bias current | I _{IB} | $V_{CM} = 0 V$ | 1 | | 1 | | All | | ±25 | nA |
| | | | | | 2, 3 | | | - | ±50 | |
| | | | M,D,P | ,L,R | 1 | | | | ±500 | - |
| Input noise voltage | En | $f_0 = 1$ Hz to 10 $T_A = +25^{\circ}C$ | 00 Hz <u>3</u> / | | 7 | | 01 | | 110 | nV RMS |
| | | | | | | | 02 | | 265 | - |
| Large-signal voltage gain | A _{VS} | $V_0 = \pm 10 \text{ V},$ $R_L = 10 \text{ k}\Omega$ | | | 4 | | 01 | 1000 | | V/mV |
| | | | | | 5, 6 | | | 750 | | - |
| | | | M,D,P | ,L,R | 4 | | | 100 | | - |
| | | $V_{O} = \pm 10 \text{ V},$ $R_{L} = 2 \text{ k}\Omega \underline{3}$ | / | | 4 | | | 500 | | |
| | | _ | | | 5, 6 | | | 400 | | - |
| | | $V_0 = \pm 10 V$, R _L = 10 kΩ | | | 4 | | 02 | 500 | | 1 |
| | | | | | 5, 6 | | | 375 | | - |
| | | | M,D,P | ,L,R | 4 | | | 50 | | 1 |
| See footnotes at end of table | | 1 | 1 | | I | | | L | I | |
| STAN MICROCIRCI | IDARD UIT DRAV | VING | | | ZE A | | | | 596 | 2-88565 |
| DLA LAND A COLUMBUS, C | ND MARITI | ME | | | | REVI | SION LEVI G | EL | SHEET | 5 |

| Test | Symbol | $\begin{array}{c c} & Conditions \ \underline{1}/ \ \underline{2}/\\ Symbol & -55^{\circ}C \leq T_{A} \leq +125^{\circ}C\\ unless \ otherwise \ specified \end{array}$ | | Group A subgroups | Device type | Limits | | Unit |
|--|---|--|--|--|---|---|--|--------------------------|
| | | | | | | Min | Max | 1 |
| Large-signal voltage gain | A _{VS} | $V_{O} = \pm 10 \text{ V},$ $R_{L} = 2 \text{ k}\Omega \underline{3}$ | <u></u> <u>3/</u> | 4 | 02 | 350 | | V/mV |
| | | | | 5, 6 | 1 | 250 | | 1 |
| Output voltage swing | V _{OP} | $R_L = 2 k\Omega \frac{3}{2}$ | 1 | 4, 5, 6 | All | ±12 | | V |
| Supply current <u>4</u> / | Is | No load | | 1, 2, 3 | All | | 11 | mA |
| | | | M,D,P,L,R | 1 | 1 | | 11 | 1 |
| Slew rate | SR | $A_{VCL} = +21, R$ $T_A = +25^{\circ}C$ | | 7 | 01 | 1.4 | | V/µs |
| | | | _ | | 02 | 6.5 | | 1 |
| Common-mode rejection | CMR | V _{CM} = IVR = ± | ±11 V <u>3</u> / <u>5</u> / | 1 | 01 | 110 | | dB |
| | | | | 2, 3 | 1 | 100 | | - |
| | | | | 1 | 02 | 105 | | - |
| | | | | 2, 3 | 1 | 100 | | 1 |
| Power supply rejection ratio | PSRR | V _{CC} = ±4.5 V | to ±18 V <u>3</u> / | 1 | 01 | | 1.8 | μV/V |
| | | | | 2, 3 | 1 | | 5.6 | 1 |
| | | | | 1 | 02 | | 5.6 | 1 |
| | | | | 2, 3 | 1 | | 10 | 1 |
| Devices supplied to this dra device is only tested at the When performing post irrad These parts may be dose ra Radiation end point limits for 1019, condition A. This parameter is not tested | "R" level. F diation electrate sensitive or the noted | Pre and Post irra trical measurem e in a space en d parameters are | adiation values ients for any RH vironment and r | are identical ur HA level, $T_A = +$ may demonstra | nless other -25°C. V _{CC} ate enhanc | rwise spe $_{c} = \pm 15 \text{ V}$ ed low do | ecified in ta /, R _S = 50 9 ose rate ef | able I. Ω. ffects. |

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|--|-----------|---------------------|------------|
| DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 | | REVISION LEVEL G | SHEET 6 |

| Device types | | 01 and 0 |)2 | |
|---|---|--|---|--|
| Case outlines | C and D | 2 | 3 | к |
| Terminal number | | Terminal s | ymbol | |
| $ \begin{array}{c} 1\\ 2\\ 3\\ 4\\ 5\\ 6\\ 7\\ 8\\ 9\\ 10\\ 11\\ 12\\ 13\\ 14\\ 15\\ 16\\ 17\\ 18\\ 19\\ 20\\ 21\\ 22\\ 23\\ 24\\ 25\\ 26\\ 27\\ 28\\ \end{array} $ | OUT A -IN A +IN A +V _{CC} +IN B -IN B OUT B OUT C -IN C +IN C -V _{CC} +IN D OUT D -IN D OUT D -IN - -IN - | NC OUT A -IN A +IN A NC +V _{CC} NC +IN B -IN B OUT B NC OUT C -IN C +IN C NC -V _{CC} NC +IN D -IN D OUT D -IN D OUT D -IN D OUT D -IN C +IN D -IN D OUT D | NC OUT A -IN A NC +IN A NC +IN A NC +V _{cc} NC +IN B NC OUT C -IN C NC -IN C NC -IN C NC +IN C NC -IN C NC -IN C NC -IN C NC -IN C -IN C -IN C -IN D OUT C -IN C -I | OUT A -IN A NC HIN A +Vcc B NC NC HIN A +Vcc B NC NC NC NC A -IN D NC NC A +Vcc D NC NC A -IN D NC NC A -IN C NC NC A -IN C NC A -IN C -IN C NC A -IN C -IN C -IN C NC A -IN C -IN C NC A -IN C -IN C -IN C -IN C NC A -IN C -IN |

FIGURE 1. Terminal connections.

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|----------------------------------|-----------|----------------|------------|
| DLA LAND AND MARITIME | | REVISION LEVEL | SHEET |
| COLUMBUS, OHIO 43218-3990 | | G | 7 |

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 <u>Verification and review for device class M</u>. For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

- 4.2.1 Additional criteria for device class M.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|----------------------------------|-----------|----------------|------------|
| DLA LAND AND MARITIME | | REVISION LEVEL | SHEET |
| COLUMBUS, OHIO 43218-3990 | | G | 8 |

| Test requirements | Subgroups (in accordance with MIL-STD-883, method 5005, table I) | Subgr (in accord MIL-PRF-385 | ance with |
|--|---|------------------------------------|------------------------------|
| | Device class M | Device class Q | Device class V |
| Interim electrical parameters (see 4.2) | 1 | 1 | 1 |
| Final electrical parameters (see 4.2) | 1,2,3,4,5,6 <u>1</u> / | 1,2,3,4,5,6 <u>1</u> / | 1,2,3,4, <u>1/ 2/</u> 5,6 |
| Group A test requirements (see 4.4) | 1,2,3,4,5,6,7 | 1,2,3,4,5,6,7 | 1,2,3,4,5,6,7 |
| Group C end-point electrical parameters (see 4.4) | 1 | 1 | 1 <u>2</u> / |
| Group D end-point electrical parameters (see 4.4) | 1 | 1 | 1 |
| Group E end-point electrical parameters (see 4.4) | | | 1, 4 |

TABLE IIA. Electrical test requirements.

<u>1</u>/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous interim electrical parameters.

| Table IIB. 240 hour burn-in and group C end-point electrical parameters. |
|--|
|--|

| Parameter | Device type | Limit | | De | elta |
|-----------------|-------------|-------|--------|-----|--------|
| | | Min | Max | Min | Max |
| V _{os} | 01 | | 0.4 mV | | 100 μV |
| | 02 | | 0.8 mV | | 250 μV |
| los | 01 | | 10 nA | | 5 nA |
| | 02 | | 10 nA | | 5 nA |
| I _B | 01 | | ±25 nA | | 5 nA |
| | 02 | | ±25 nA | | 5 nA |

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|----------------------------------|-----------|----------------|------------|
| DLA LAND AND MARITIME | | REVISION LEVEL | SHEET |
| COLUMBUS, OHIO 43218-3990 | | G | 9 |

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
- 4.4.2 <u>Group C inspection</u>. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - b. $T_A = +125^{\circ}C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^{\circ}C \pm 5^{\circ}C$, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A and as specified herein.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractorprepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

| STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 | SIZE A | | 5962-88565 |
|--|-----------|---------------------|-------------|
| | | REVISION LEVEL G | SHEET 10 |

6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-0544.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

| STANDARD MICROCIRCUIT DRAWING | SIZE A | | 5962-88565 |
|----------------------------------|-----------|----------------|------------|
| DLA LAND AND MARITIME | | REVISION LEVEL | SHEET |
| COLUMBUS, OHIO 43218-3990 | | G | 11 |

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 11-04-06

Approved sources of supply for SMD 5962-88565 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

| Standard microcircuit drawing PIN <u>1</u> / | Vendor CAGE number | Vendor similar PIN <u>2</u> / |
|--|--------------------------|-------------------------------------|
| 5962-8856501CA | 24355 (2) | OP-470AY/883C |
| 5962-88565012A | 24355 (2) | OP-470ARC/883C |
| 5962-88565013A | <u>3</u> / | OP-470ATC/883C |
| 5962-8856502CA | 24355 (2) | OP-471AY/883C |
| 5962-88565022A | 24355 (2) | OP-471ARC/883C |
| 5962-88565023A | 24355 (2) | OP-471ATC/883C |
| 5962-8856501VCA | 24355 (4) | OP470AY/QMLV |
| 5962-8856501V2A | 24355 (4) | OP470ARC/QMLV |
| 5962-8856501VKA | 24355 (4) | OP470AN/QMLV |
| 5962-8856502VCA | 24355 (4) | OP471AY/QMLV |
| 5962-8856502VDA | 24355 (4) | OP471AM/QMLV |
| 5962-8856502V2A | <u>3</u> / | OP471ARC/QMLV |
| 5962-8856502VKA | 24355 (4) | OP471AN/QMLV |
| | | |

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING BULLETIN - CONTINUED

| Standard microcircuit drawing PIN <u>1</u> / | Vendor CAGE number | Vendor similar PIN <u>2</u> / |
|--|--------------------------|-------------------------------------|
| 5962R8856501VCA | 24355 (4) | OP470AY/QMLR |
| 5962R8856501V2A | 24355 (4) | OP470ARC/QMLR |
| 5962R8856501VKA | 24355(4) | OP470AN/QMLR |
| 5962R8856502VCA | 24355 (4) | OP471AY/QMLR |
| 5962R8856502VDA | 24355 (4) | OP471AM/QMLR |
| 5962R8856502V2A | <u>3</u> / | OP471ARC/QMLR |
| 5962R8856502VKA | 24355 (4) | OP471AN/QMLR |

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

<u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

 $\underline{3}$ / Not available from an approved source of supply.

Vendor CAGE Vendor name and address number 24355 Analog Devices (2) RT 1 Industrial Park PO Box 9106 Norwood, MA 02062 Point of contact: 804 Woburn Street Wilmington, MA 01887-3462 24355 Analog Devices (4) RT 1 Industrial Park PO Box 9106 Norwood, MA 02062 Point of contact: 7910 Triad Center Drive Greensboro, NC 27409-9605

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.